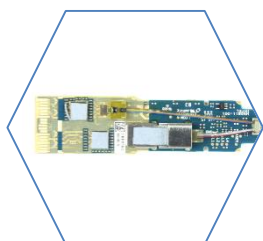
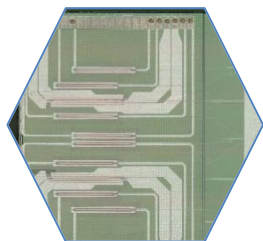


Intel Silicon Photonic 100G PSM4 QFSP28 Transceiver

Deep analysis of the first silicon photonic die with Intel's unique approach for laser integration, the outcome of 15 years of development, along with the main optoelectronic components in the connector.



In only a few years, Intel has become the number two supplier for silicon photonics-based optical transceivers. Intel has succeeded because it put a lot of effort into the bottleneck, which was integrating the laser chip through InP chiplet bonding followed by post processing. Intel introduced a silicon photonics Quad Small Form-factor Pluggable (QSFP) format transceiver that supports 100G communications in 2016. The company now ships a million units of this product per year into data centers. Intel's 400G products are expected to enter volume production in the second half of 2019. At ECOC 2018, Intel announced new 100G silicon photonics transceivers targeted at 5G wireless fronthaul applications. All these innovations have been enabled by Intel's first generation 100G series silicon photonics QSFP transceivers, featuring laser-on-chip integration.

The transceiver contains two separate blocks, each with several dies. The transmitter integrates several InP lasers and a CMOS die chiplets through bonding on the main silicon die in flip-chip configuration. On the main silicon die a Mach-Zehnder modulator encodes signals. Other components focus or isolate the signals. Data are processed using a four-channel 25G optical Clock and Data Recovery (CDR) component from MACOM. The receiver function is performed by four germanium (Ge) photodiode dies and a TransImpedance Amplifier (TIA) circuit. The Ge photo-diodes are manufactured on a dedicated Silicon-on-Insulator substrate. A fiber-optical coupler with focusing lens connects the photodiode die with the fiber optic.

All of these components – described in this report – show Intel's potential in terms of packaging and photonics. In a very small form factor, Intel manages to integrate four lasers, a photonic driver, optical modules, CDR functionality, high performance photodiodes, two advanced substrates and materials for optics. This report will show how the company implements the chiplet configuration, and provides a detailed description of the transmitter and receiver line.

This report is exhaustive analysis of the main components of the Intel 100G PSM4 connector, including a full analysis of the silicon photonic die, the TIA circuit, the Mach-Zehnder driver circuit, the MACOM circuit and the germanium photodiode along with a cost analysis and price estimate. It also describes the two fiber optic couplers, focusing lens and the isolator and estimates their price. We also compare the product against Luxtera's silicon photonic circuit.

Title: Intel Silicon Photonic 100G PSM4 QFSP28

Pages: 200

Date: March 2019

Format:
PDF & Excel file

Price:
EUR 3,990

COMPLETE TEARDOWN WITH

- Detailed photos
- Precise measurements
- Materials analysis
- Manufacturing process flow
- Supply chain evaluation
- Manufacturing cost analysis
- Comparison
- Didactic explanation of device operation
- Estimated sales price

TABLE OF CONTENTS

Overview/Introduction

Intel Company Profile

Physical Analysis

- Physical Analysis Methodology
- PSM4 Connector Teardown
- Transmitter Block
 - View, dimensions, light path, cross-section
- MZI Driver Die
- Silicon Photonic Die
 - Die overview and dimensions
 - InP laser process and cross-section
 - MZI process and cross-section
 - Mirror process and cross-section
 - Waveguide process and cross-section
 - Die process characteristic
- Receiver Block
 - View, dimensions, light path, cross-section
- Germanium Photodiode
 - Die view and dimensions, process and cross-section
- TIA Die
- MACOM MG37049G Die

Comparison Intel – Luxtera Silicon Photonics Dies

Manufacturing Process Flow

- MZI Driver Die Front-End Process and Fabrication Unit
- Silicon Photonic Die Process Flow

- Silicon Photonic Die Front-End Fabrication Unit
- Receiver Fiber Optic coupler, Process Flow and Cost
- Germanium Photodiode Die Process Flow and Fabrication Unit
- TIA Die Front-End Process and Fabrication Unit
- MACOM M37049G Die Front-End Process and Fabrication Unit

Cost Analysis

- Summary of the Cost Analysis
- Yields Explanation and Hypotheses
- Transmitter Block
 - Silicon photonic die
 - Wafer cost
 - Step cost
 - Die cost
 - MZI driver die
 - MACOM M37049G
 - Optical elements
 - Assembly
- Receiver Block
 - Germanium photodiode die
 - TIA die
 - MACOM M37049G
 - Optical element
 - Assembly

Estimated Price Analysis: Transmitter Block and Receiver Block

AUTHORS



Sylvain Hallereau is in charge of costing analyses for IC, power and MEMS. He has more than 10 years of experience in power device manufacturing cost analysis and has studied a wide range of technologies.



Nicolas Radufe is in charge of physical analysis at System Plus Consulting. He has a deep knowledge in chemical and physical analyses. He previously worked in microelectronics R&D for CEA/LETI in Grenoble and for STMicroelectronics in Crolles.

RELATED REPORTS



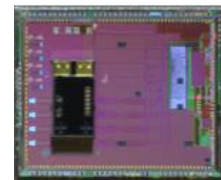
Mobile Camera Module Comparison 2019

Physical analysis and cost comparison of seven leading flagship smartphone cameras: Apple iPhone X/XS/XR, Samsung Galaxy S9, Huawei Mate 20 Pro and P20 Pro...
January 2019 - EUR 6,490*



Mantis Vision's 3D Depth Sensing System in the Xiaomi Mi8 Explorer Edition

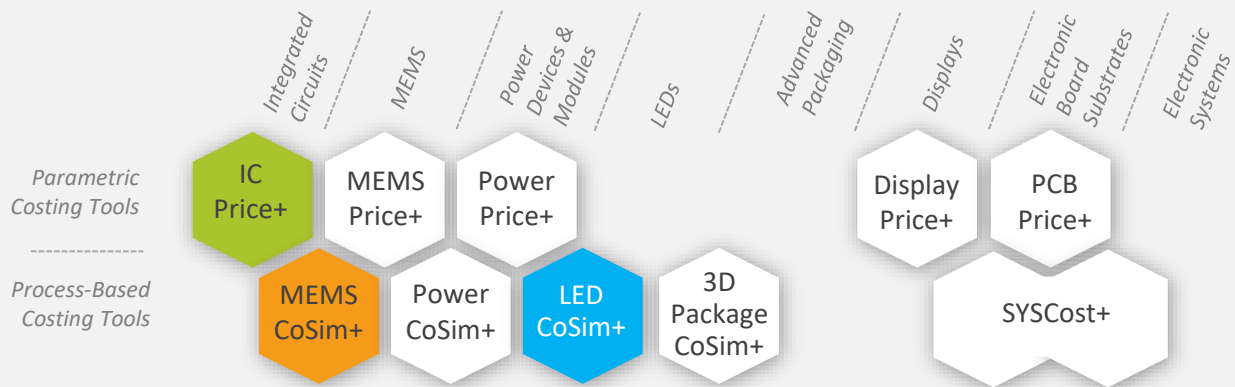
The first introduction of Mantis Vision's technology into a mobile application, featuring coded structured light.
December 2018 - EUR 3,990*



MOLEX – Luxtera Silicon Photonic Die

The 1064101003 Quad Small Form-factor Pluggable Plus connector from Molex integrates this photonic circuit from Luxtera.
November 2012 - EUR 2,990*

COSTING TOOLS



Our analysis is performed with our costing tools MEMS CoSim+, IC Price+ and LED CoSim+.

System Plus Consulting offers powerful costing tools to evaluate the production cost and selling price from single chip to complex structures.

LED CoSim+

Process based costing tool used to evaluate the manufacturing cost per wafer using your own inputs or using the predefined parameters included in the tool.

MEMS CoSim+

Cost simulation tool to evaluate the cost of any MEMS process or device.

IC Price+

Performs the necessary cost simulation of any Integrated Circuit: ASICs, microcontrollers, memories, DSP, smartpower...

WHAT IS A REVERSE COSTING®?

Reverse Costing® is the process of disassembling a device (or a system) in order to identify its technology and calculate its manufacturing cost, using in-house models and tools.



CONTACTS

Headquarters

22, bd Benoni Goullin
Nantes Biotech
44200 Nantes
France
+33 2 40 18 09 16
sales@systemplus.fr

Europe Sales Office

Lizzie LEVENEZ
Frankfurt am Main
Germany
+49 151 23 54 41 82
llevenez@systemplus.fr

America Sales Office

Steven LAFERRIERE
Western USA & Canada
+1 310-600-8267
laferriere@yole.fr

Chris YOUMAN
Eastern USA & Canada
+1 919-607-9839
chris.youman@yole.fr

Asia Sales Office

Takashi ONOZAWA
Japan & Rest of Asia
+81 3 4405 9204
onozawa@yole.fr

Mavis WANG
Greater China
+886 979 336 809
wang@yole.fr

ABOUT SYSTEM PLUS CONSULTING

System Plus Consulting is specialized in the cost analysis of electronics from semiconductor devices to electronic systems.

A complete range of services and costing tools to provide in-depth production cost studies and to estimate the objective selling price of a product is available.

Our services:

- **STRUCTURE & PROCESS ANALYSES**
- **CUSTOM ANALYSES**
- **COSTING SERVICES**
- **COSTING TOOLS**
- **TRAININGS**

www.systemplus.fr
sales@systemplus.fr

ORDER FORM

Please process my order for “Intel Silicon Photonic 100G PSM4 QFSP28 Transceiver” Reverse Costing® – Structure, Process & Cost Report

Ref: SP19407

- ☐ **Full Structure, Process & Cost Report :** EUR 3,990*
- ☐ **Annual Subscription offers possible from 3 reports, including this report as the first of the year. Contact us for more information.**

SHIP TO

Name (Mr/Ms/Dr/Pr):

Job Title:

Company:

Address:

City: State:

Postcode/Zip:

Country:

VAT ID Number for EU members:

Tel:

Email:

Date:

Signature:

BILLING CONTACT

First Name :

Last Name:

Email:

Phone:

PAYMENT

By credit card:

Number: |_|_|_|_| |_|_|_|_| |_|_|_|_|
|_|_|_|_|

Expiration date: |_|_|/|_|_|

Card Verification Value: |_|_|_|_|

By bank transfer:

HSBC - CAE- Le Terminal -2 rue du Charron - 44800 St Herblain France
BIC code: CCFRFRPP

• In EUR

Bank code : 30056 - Branch code : 00955 - Account :
09550003234

IBAN: FR76 3005 6009 5509 5500 0323 439

• In USD

Bank code : 30056 - Branch code : 00955 - Account :
09550003247

IBAN: FR76 3005 6009 5509 5500 0324 797

Return order by:

FAX: +33 2 53 55 10 59

MAIL: SYSTEM PLUS CONSULTING

22, bd Benoni Goullin

Nantes Biotech

44200 Nantes – France

EMAIL: sales@systemplus.fr

**For price in dollars please use the day's exchange rate*

**All reports are delivered electronically in pdf format*

**For French customer, add 20 % for VAT*

**Our prices are subject to change. Please*

check our new releases and price

changes on www.systemplus.fr. The

present document is valid 6 months after

its publishing date: March 2019

ANNUAL SUBSCRIPTIONS

Each year System Plus Consulting releases a comprehensive collection of new reverse engineering and costing analyses in various domains. You can choose to buy over 12 months a set of 3, 4, 5, 7, 10 or 15 Reverse Costing® reports.

Up to 47% discount!

More than 60 reports released each year on the following topics (considered for 2018):

- **MEMS & Sensors:** Accelerometer – Environment - Fingerprint - Gas - Gyroscope - IMU/Combo - Microphone - Optics - Oscillator - Pressure
- **Power:** GaN - IGBT - MOSFET - Si Diode - SiC
- **Imaging:** Camera - Spectrometer
- **LED and Laser:** UV LED – VCSEL - White/blue LED
- **Packaging:** 3D Packaging - Embedded - SIP - WLP
- **Integrated Circuits:** IPD – Memories – PMIC - SoC
- **RF:** FEM - Duplexer
- **Systems:** Automotive - Consumer - Energy - Telecom

TERMS AND CONDITIONS OF SALES

1.INTRODUCTION

The present terms and conditions apply to the offers, sales and deliveries of services managed by System Plus Consulting except in the case of a particular written agreement.

Buyer must note that placing an order means an agreement without any restriction with these terms and conditions.

2.PRICES

Prices of the purchased services are those which are in force on the date the order is placed. Prices are in Euros and worked out without taxes. Consequently, the taxes and possible added costs agreed when the order is placed will be charged on these initial prices.

System Plus Consulting may change its prices whenever the company thinks it necessary. However, the company commits itself in invoicing at the prices in force on the date the order is placed.

3.REBATES and DISCOUNTS

The quoted prices already include the rebates and discounts that System Plus Consulting could have granted according to the number of orders placed by the Buyer, or other specific conditions. No discount is granted in case of early payment.

4.TERMS OF PAYMENT

System Plus Consulting delivered services are to be paid within 30 days end of month by bank transfer except in the case of a particular written agreement.

If the payment does not reach System Plus Consulting on the deadline, the Buyer has to pay System Plus Consulting a penalty for late payment the amount of which is three times the legal interest rate. The legal interest rate is the current one on the delivery date. This penalty is worked out on the unpaid invoice amount, starting from the invoice deadline. This penalty is sent without previous notice.

When payment terms are over 30 days end of month, the Buyer has to pay a deposit which amount is 10% of the total invoice amount when placing his order.

5. OWNERSHIP

System Plus Consulting remains sole owner of the delivered services until total payment of the invoice.

6.DELIVERIES

The delivery schedule on the purchase order is given for information only and cannot be strictly guaranteed. Consequently any reasonable delay in the delivery of services will not allow the buyer to claim for damages or to cancel the order.

7.ENTRUSTED GOODS SHIPMENT

The transport costs and risks are fully born by the Buyer. Should the customer wish to ensure the goods against lost or damage on the base of their real value, he must imperatively point it out to System Plus Consulting when the shipment takes place. Without any specific requirement, insurance terms for the return of goods will be the carrier current ones (reimbursement based on good weight instead of the real value).

8.FORCE MAJEURE

System Plus Consulting responsibility will not be involved in non execution or late delivery of one of its duties described in the current terms and conditions if these are the result of a force majeure case. Therefore, the force majeure includes all external event unpredictable and irresistible as defined by the article 1148 of the French Code Civil?

9.CONFIDENTIALITY

As a rule, all information handed by customers to system Plus Consulting are considered as strictly confidential. A non-disclosure agreement can be signed on demand.

10.RESPONSABILITY LIMITATION

The Buyer is responsible for the use and interpretations he makes of the reports delivered by System Plus Consulting. Consequently, System Plus Consulting responsibility can in no case be called into question for any direct or indirect damage, financial or otherwise, that may result from the use of the results of our analysis or results obtained using one of our costing tools.

11.APPLICABLE LAW

Any dispute that may arise about the interpretation or execution of the current terms and conditions shall be resolved applying the French law.

It the dispute cannot be settled out-of-court, the competent Court will be the Tribunal de Commerce de Nantes.